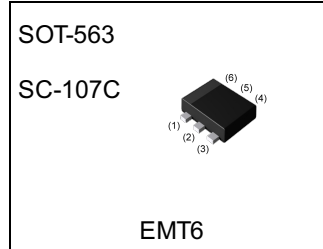


| Parameter | Tr1 and Tr2 |
|-----------|-------------|
| V_{CEO} | -50V |
| I_C | -150mA |

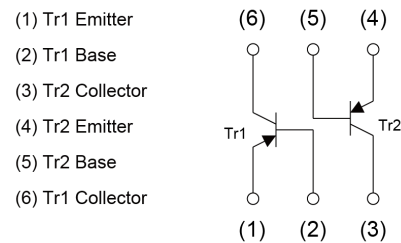
●Outline



●Features

- 1)Two 2SA1037AK chips in a EMT package.
- 2)Mounting possible with EMT3 automatic mounting machines.
- 3)Transistor elements are independent, eliminating interference.
- 4)Mounting cost and area can be cut in half.

●Inner circuit



●Application

GENERAL PURPOSE SMALL SIGNAL AMPLIFIER

●Packaging specifications

| Part No. | Package | Package size | Taping code | Reel size (mm) | Tape width (mm) | Basic ordering unit.(pcs) | Marking |
|----------|----------------|--------------|-------------|----------------|-----------------|---------------------------|---------|
| EMT1 FHA | SOT-563 (EMT6) | 1616 | T2R | 180 | 8 | 8000 | T1 |

● **Absolute maximum ratings** ($T_a = 25^\circ\text{C}$) <It is the same ratings for the Tr1 and Tr2>

| Parameter | Symbol | Values | Unit | |
|------------------------------|-----------|-------------|------------------|----|
| Collector-base voltage | V_{CBO} | -60 | V | |
| Collector-emitter voltage | V_{CEO} | -50 | V | |
| Emitter-base voltage | V_{EBO} | -6 | V | |
| Collector current | I_C | -150 | mA | |
| Power dissipation | total | P_D^{*1} | 150 | mW |
| | element | P_D | 120 | mW |
| Junction temperature | T_j | 150 | $^\circ\text{C}$ | |
| Range of storage temperature | T_{stg} | -55 to +150 | $^\circ\text{C}$ | |

● **Electrical characteristics** ($T_a = 25^\circ\text{C}$) <It is the same characteristics for the Tr1 and Tr2>

| Parameter | Symbol | Conditions | Values | | | Unit |
|--------------------------------------|---------------|---|--------|------|------|------|
| | | | Min. | Typ. | Max. | |
| Collector-base breakdown voltage | BV_{CBO} | $I_C = -50\mu\text{A}$ | -60 | - | - | V |
| Collector-emitter breakdown voltage | BV_{CEO} | $I_C = -1\text{mA}$ | -50 | - | - | V |
| Emitter-base breakdown voltage | BV_{EBO} | $I_E = -50\mu\text{A}$ | -6 | - | - | V |
| Collector cut-off current | I_{CBO} | $V_{CB} = -60\text{V}$ | - | - | -100 | nA |
| Emitter cut-off current | I_{EBO} | $V_{EB} = -6\text{V}$ | - | - | -100 | nA |
| Collector-emitter saturation voltage | $V_{CE(sat)}$ | $I_C = -50\text{mA}, I_B = -5\text{mA}$ | - | - | -500 | mV |
| DC current gain | h_{FE} | $V_{CE} = -6\text{V}, I_C = -1\text{mA}$ | 120 | - | 560 | - |
| Transition frequency | f_T | $V_{CE} = -12\text{V}, I_E = 2\text{mA}, f = 100\text{MHz}$ | - | 140 | - | MHz |
| Output capacitance | C_{ob} | $V_{CB} = -12\text{V}, I_E = 0\text{A}, f = 1\text{MHz}$ | - | 4 | 5 | pF |

*1 Each terminal mounted on a reference land.

● Electrical characteristic curves ($T_a = 25^\circ\text{C}$)

<For Tr1 and Tr2 in common>

Fig.1 Ground Emitter Propagation Characteristics

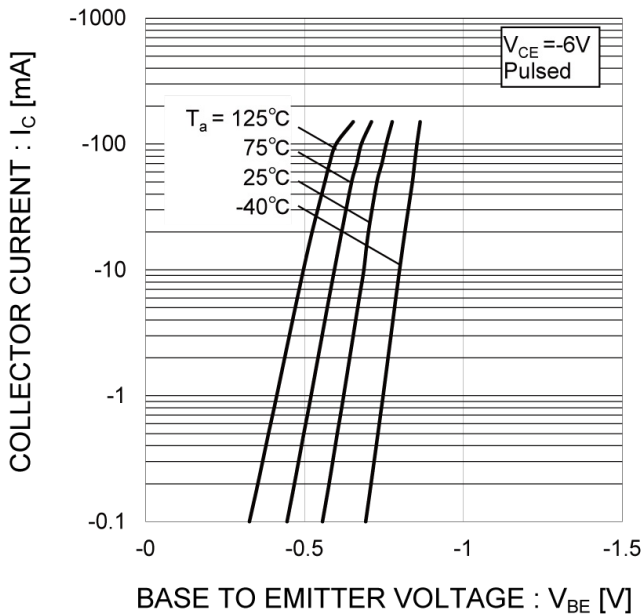


Fig.2 Grounded Emitter Output Characteristics

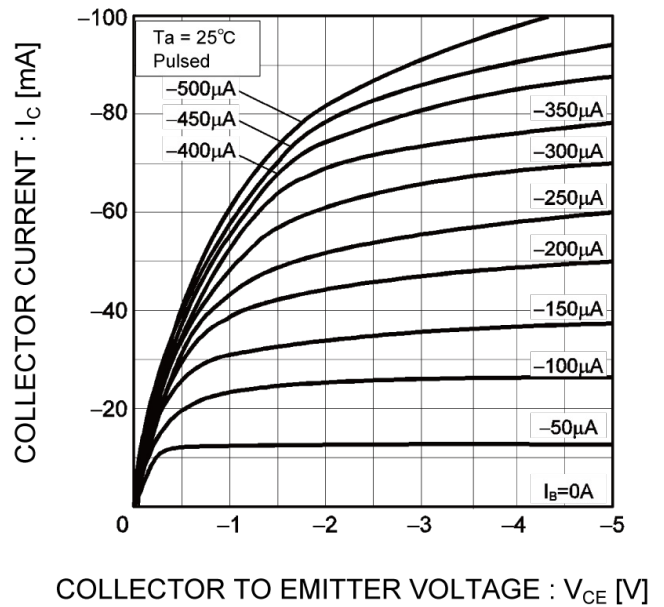


Fig.3 DC Current Gain vs. Collector Current (I)

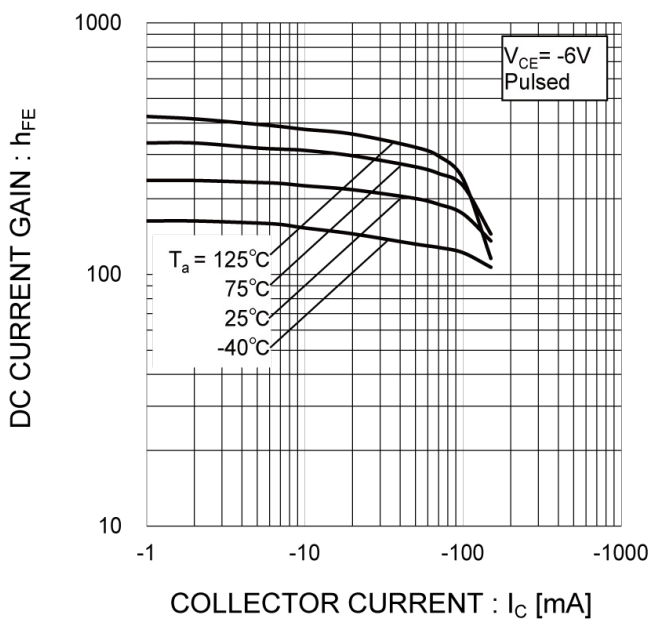
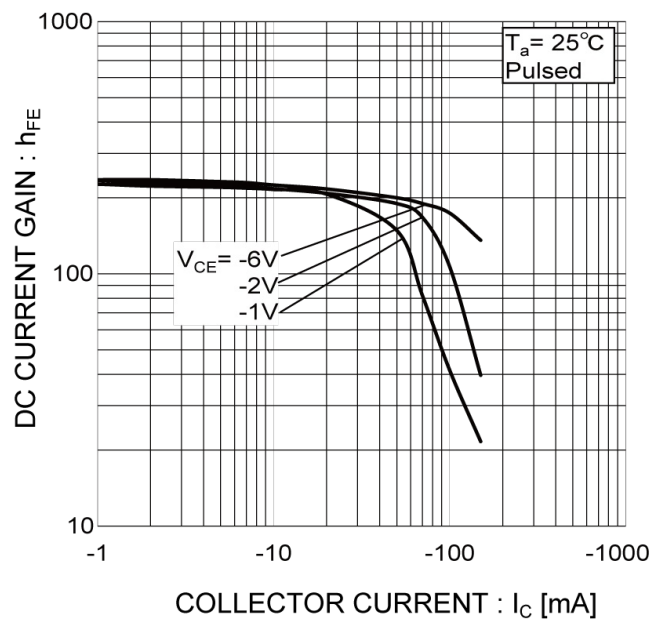


Fig.4 DC Current Gain vs. Collector Current (II)



● **Electrical characteristic curves** ($T_a = 25^\circ\text{C}$)

<For Tr1 and Tr2 in common>

Fig.5 Collector-Emitter Saturation Voltage vs. Collector Current(I)

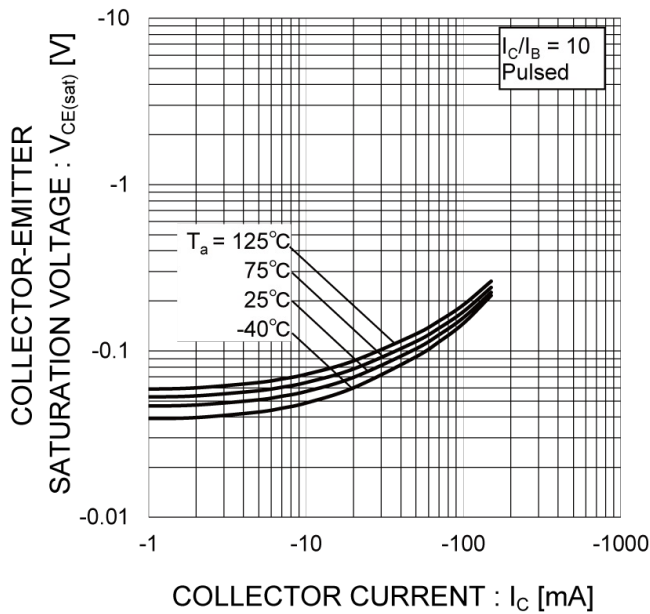


Fig.6 Collector-Emitter Saturation Voltage vs. Collector Current(II)

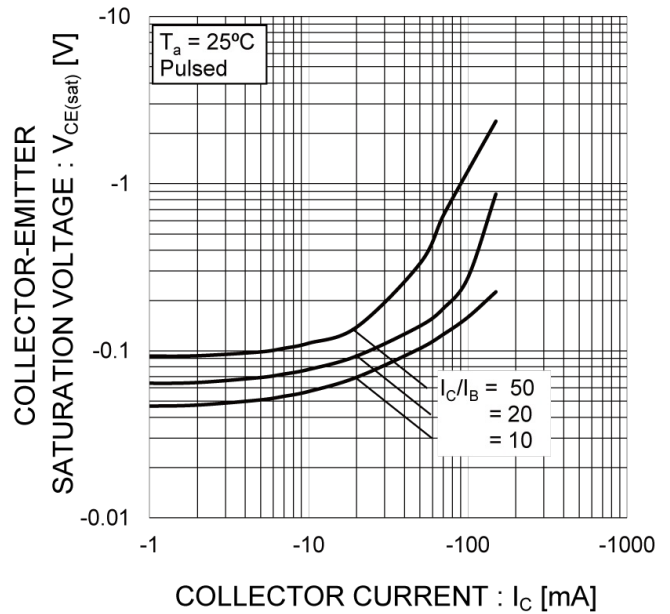


Fig.7 Base-Emitter Saturation Voltage vs. Collector Current (I)

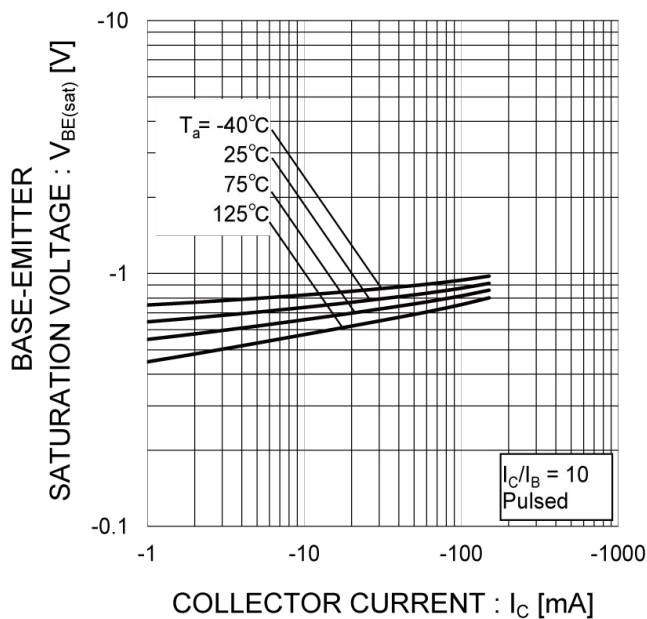
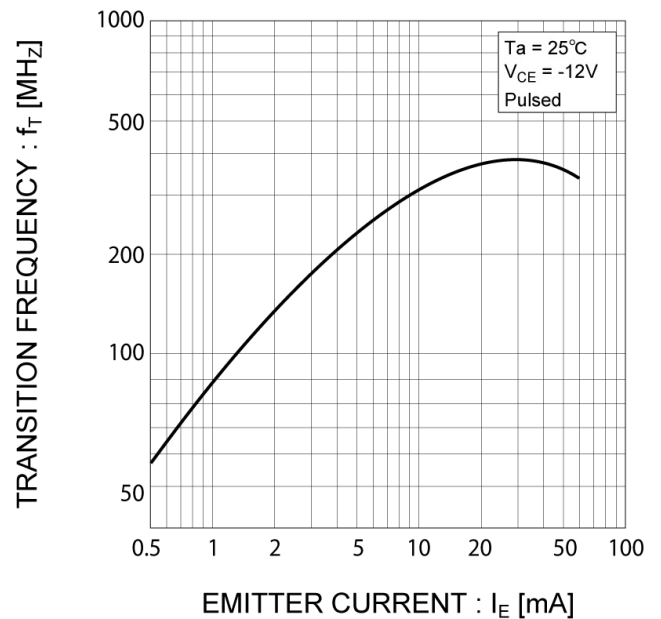


Fig.8 Gain Bandwidth Product vs. Emitter Current



● **Electrical characteristic curves** ($T_a = 25^\circ\text{C}$)

<For Tr1 and Tr2 in common>

Fig.9 Collector Output Capacitance vs. Collector-Base Voltage
 Emitter Input Capacitance vs. Emitter-Base Voltage

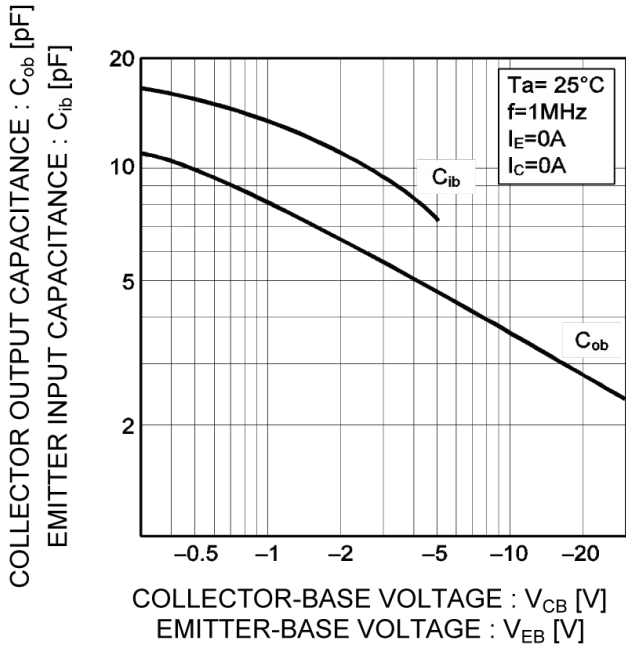
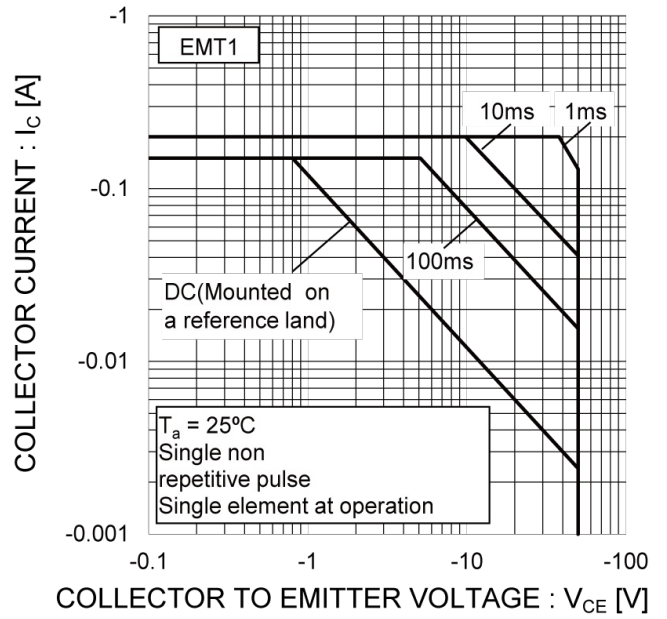
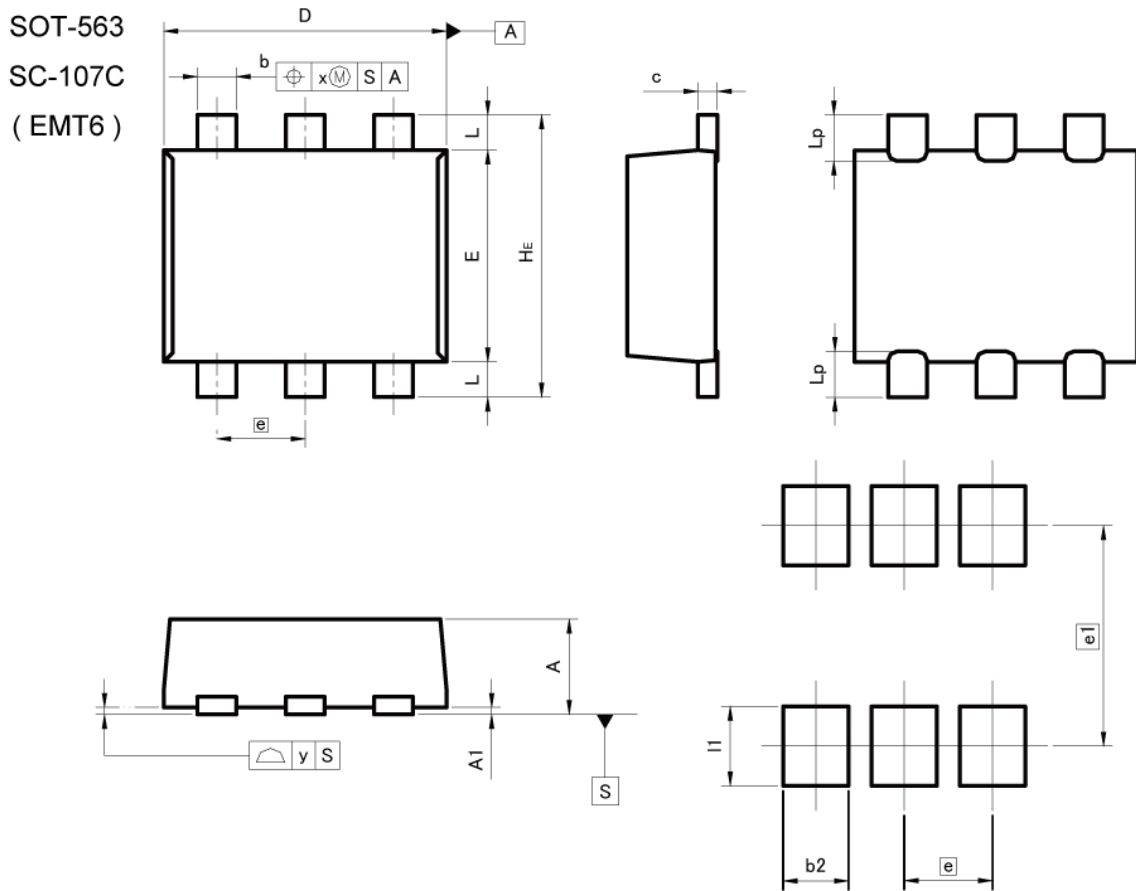


Fig.10 Safe Operating Area



●Dimensions



Pattern of terminal position areas
[Not a pattern of soldering pads]

| DIM | MILIMETERS | | INCHES | |
|-----|------------|------|--------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.45 | 0.55 | 0.018 | 0.022 |
| A1 | 0.00 | 0.10 | 0.000 | 0.004 |
| b | 0.17 | 0.27 | 0.007 | 0.011 |
| c | 0.08 | 0.18 | 0.003 | 0.007 |
| D | 1.50 | 1.70 | 0.059 | 0.067 |
| E | 1.10 | 1.30 | 0.043 | 0.051 |
| e | 0.50 | | 0.020 | |
| HE | 1.50 | 1.70 | 0.059 | 0.067 |
| L | 0.10 | 0.30 | 0.004 | 0.012 |
| Lp | - | 0.35 | - | 0.014 |
| x | - | 0.10 | - | 0.004 |
| y | - | 0.10 | - | 0.004 |

| DIM | MILIMETERS | | INCHES | |
|-----|------------|------|--------|-------|
| | MIN | MAX | MIN | MAX |
| b2 | - | 0.37 | - | 0.015 |
| e1 | 1.25 | | 0.049 | |
| I1 | - | 0.45 | - | 0.018 |

Dimension in mm/inches

Notice

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1. If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ^(Note 1), aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

| JAPAN | USA | EU | CHINA |
|-----------|-----------|------------|-----------|
| CLASS III | CLASS III | CLASS II b | CLASS III |
| CLASS IV | | CLASS III | |

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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
4. The Products are not subject to radiation-proof design.
5. Please verify and confirm characteristics of the final or mounted products in using the Products.
6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
8. Confirm that operation temperature is within the specified range described in the product specification.
9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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